

To all our customers

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Renesas Technology Corp.  
Customer Support Dept.  
April 1, 2003

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Keep safety first in your circuit designs!

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# HD74HC113

## Dual J-K Flip-Flops (with Preset)



ADE-205-436 (Z)

1st. Edition

Sep. 2000

### Description

This flip-flop is edge sensitive to the clock input and change state on the negative going transition of the clock pulse. Each one has independent J, K, clock, and preset inputs and Q and  $\bar{Q}$  outputs. Preset is independent of the clock and accomplished by a low level on the input.

### Features

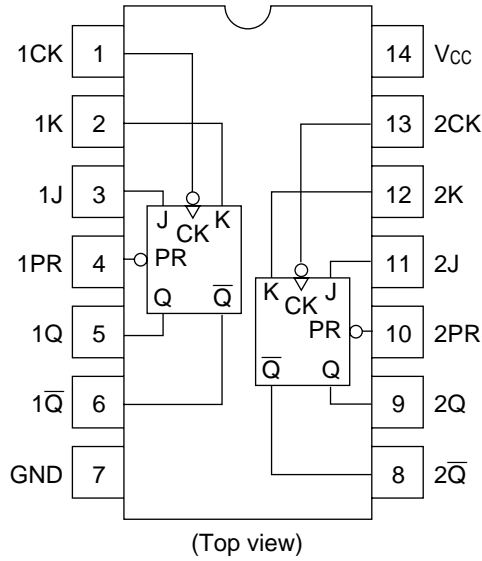
- High Speed Operation:  $t_{pd}$  (Clock to Q) = 18 ns typ ( $C_L = 50$  pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage:  $V_{CC} = 2$  to 6 V
- Low Input Current: 1  $\mu$ A max
- Low Quiescent Supply Current:  $I_{CC}$  (static) = 2  $\mu$ A max ( $T_a = 25^\circ\text{C}$ )

### Function Table

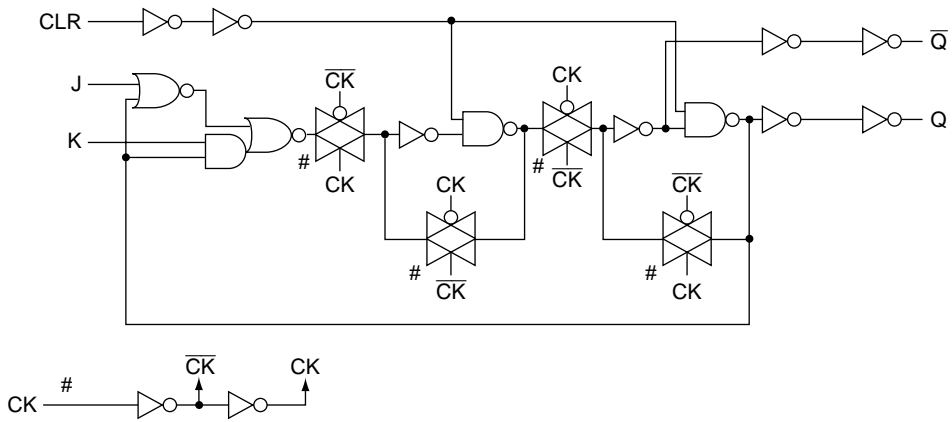
Inputs				Output	
Preset	Clock	J	K	Q	$\bar{Q}$
L	X	X	X	H	L
H		L	L	No change	
H		L	H	L	H
H		H	L	H	L
H		H	H	Toggle	
H	H	X	X	No change	
H	L	X	X	No change	
H		X	X	No change	

# HD74HC113

## Pin Arrangement



## Logic Diagram (1/2)



DC Characteristics

Item	Symbol	V <sub>CC</sub> (V)	Ta = 25°C		Ta = -40 to +85°C		Unit	Test Conditions		
			Min	Typ	Max	Min			Max	
Input voltage	V <sub>IH</sub>	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V <sub>IL</sub>	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V <sub>OH</sub>	2.0	1.9	2.0	—	1.9	—	V	Vin = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -20 μA	
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—			I <sub>OH</sub> = -4 mA
		6.0	5.68	—	—	5.63	—			I <sub>OH</sub> = -5.2 mA
		V <sub>OL</sub>	2.0	—	0.0	0.1	—			0.1
	4.5		—	0.0	0.1	—	0.1			
	6.0		—	0.0	0.1	—	0.1			
	4.5		—	—	0.26	—	0.33	I <sub>OL</sub> = 4 mA		
	6.0	—	—	0.26	—	0.33	I <sub>OL</sub> = 5.2 mA			
Input current	I <sub>in</sub>	6.0	—	—	±0.1	—	±1.0	μA	Vin = V <sub>CC</sub> or GND	
Quiescent supply current	I <sub>CC</sub>	6.0	—	—	2.0	—	20	μA	Vin = V <sub>CC</sub> or GND, I <sub>out</sub> = 0 μA	

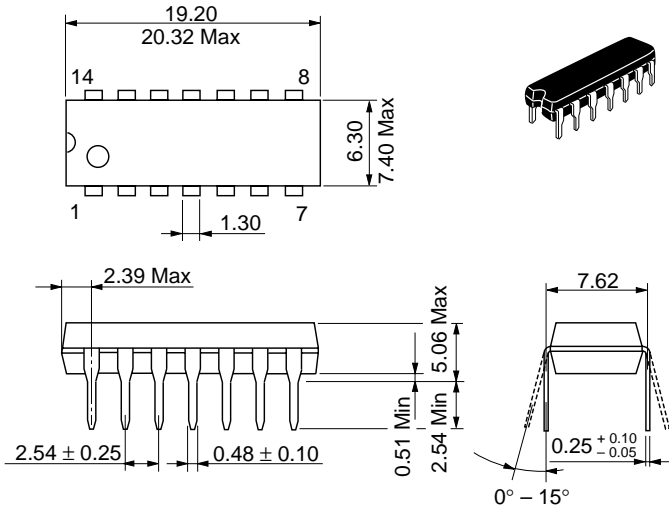
# HD74HC113

## AC Characteristics ( $C_L = 50$ pF, Input $t_r = t_f = 6$ ns)

Item	Symbol	$V_{CC}$ (V)	$T_a = 25^\circ\text{C}$			$T_a = -40$ to $+85^\circ\text{C}$		Unit	Test Conditions
			Min	Typ	Max	Min	Max		
Maximum clock frequency	$f_{max}$	2.0	—	—	6	—	5	MHz	
		4.5	—	—	30	—	24		
		6.0	—	—	35	—	28		
Propagation delay time	$t_{PLH}$	2.0	—	—	150	—	190	ns	Clock to Q or $\bar{Q}$
		4.5	—	18	30	—	38		
	$t_{PHL}$	6.0	—	—	26	—	33		Preset to Q or $\bar{Q}$
		2.0	—	—	140	—	175		
		4.5	—	17	28	—	35		
		6.0	—	—	24	—	30		
Pulse width	$t_w$	2.0	80	—	—	100	—	ns	Clock, Preset
		4.5	16	8	—	20	—		
		6.0	14	—	—	17	—		
Setup time	$t_{su}$	2.0	100	—	—	125	—	ns	J or K to Clock
		4.5	20	4	—	25	—		
		6.0	17	—	—	21	—		
Hold time	$t_h$	2.0	5	—	—	5	—	ns	Clock to J or K
		4.5	5	-2	—	5	—		
		6.0	5	—	—	5	—		
Removal time	$t_{rem}$	2.0	100	—	—	125	—	ns	Preset to Clock
		4.5	20	-2	—	25	—		
		6.0	17	—	—	21	—		
Output rise/fall time	$t_{TLH}$	2.0	—	—	75	—	95	ns	
		4.5	—	5	15	—	19		
	$t_{THL}$	6.0	—	—	13	—	16		
Input capacitance	$C_{in}$	—	—	5	10	—	10	pF	

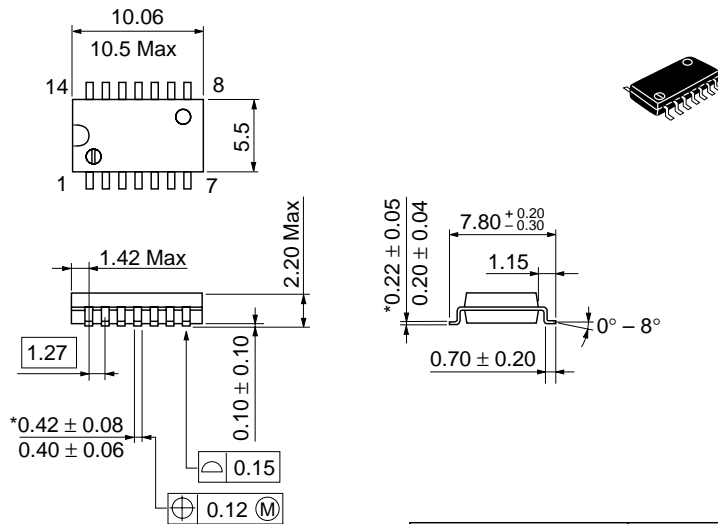
Package Dimensions

Unit: mm



Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.97 g

Unit: mm



\*Dimension including the plating thickness  
Base material dimension

Hitachi Code	FP-14DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.23 g

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